

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1–26. (Canceled)

27. (Currently Amended) A wafer double-side polishing apparatus comprising:

a carrier plate having wafer holding holes, a center of each wafer holding hole disposed along a first pitch circle having a first diameter;
upper and lower turn tables to which polishing pads are attached; and
a slurry supply means;

wherein:

with wafers held in the wafer holding holes, the carrier plate being moved between the upper and lower turn tables while supplying slurry, to simultaneously polish both front and back surfaces of wafers;

the upper turn table further comprising a plurality of load supporting points disposed along a second pitch circle having a second diameter equal to the first diameter, the load supporting points configured to receive and distribute applied force to the upper turn-table. table;

the lower turn table further comprising a plurality of load supporting points disposed along a third pitch circle having a third diameter equal to the first diameter, the load supporting points configured to receive and distribute applied force to the lower turn table.

28. (Previously Presented) The wafer double-side polishing apparatus according to claim 27, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.

29–31. (Canceled)

32. (Currently Amended) A wafer double-side polishing method comprising:

holding wafers on a carrier plate having wafer holding holes for holding wafers, a center of each wafer holding hole disposed along a first pitch circle having a first diameter; and

moving the carrier plate between upper and lower turn tables to which polishing pads are attached, while supplying slurry, to simultaneously polish both front and back surfaces of the wafers;

wherein:

the upper turn table further comprising a plurality of load supporting points disposed along a second pitch circle having a second diameter equal to the first diameter, the load supporting points configured to receive and distribute applied force to the upper turn table; and

the lower turn table further comprising a plurality of load supporting points disposed along a third pitch circle having a third diameter equal to the first diameter, the load supporting points configured to receive and distribute applied force to the lower turn table; and

the wafers are polished while applying force to the load supporting points of the upper turn table and while applying force to the load supporting points of the lower turn table.

33. (Previously Presented) The wafer double-side polishing method according to claim 32, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.

34–36. (Canceled)

37. (Previously Presented) The wafer double-side polishing method according to claim 32, wherein during the wafer polishing, the wafers are polished while controlling polishing conditions.

38. (Canceled)

39. (Previously Presented) The wafer double-side polishing method according to claim 37, wherein the polishing condition control is performed by controlling the temperature of the upper turn table and/or the lower turn table.

40–63. (Canceled)